

SANYO Semiconductors

DATA SHEET

An ON Semiconductor Company

LC749402BG—Silicon gate

Silicon gate
LCD Picture Quality
Improvement IC

Overview

LC749402BG is a picture quality improvement IC that processes the output signals to the LCD panel for high picture quality display. This IC performs various picture quality adjustments to provide the ideal correction for the display panel. It can support up to WVGA/SVGA panels. *

Features

- (1) Digital input/output
- Digital YCbCr/YPbPr 24bit (4:4:4) or 16bit (4:2:2) or 8bit(ITU-R BT.656) signal input
- Digital RGB 24bit signal input
- Digital RGB 18bit/24bit signal output
- Digital YCbCr16bit (4:2:2)/24bit (4:4:4) signal output
- (2) Image quality correction
- Y image quality correction: luminance adjustment, contour correction, CDEX (Color Depth Expander), dynamic-γ, black/white stretch
- C image quality correction: color exciter, flesh tone correction, hue, color gain
- RGB image quality correction: brightness, contrast, white balance, black balance, γ correction
- (3) Panel interface
- Built-in panel driver timing controller
- Panel protection timing signal generation
- Backlight control PWM (video adaptive low power consumption processing)
- *: The LC749402BG video input should satisfy the following conditions: 40MHz or less operating frequency, 896 dots or less horizontal size, 768 lines or less vertical size.
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LSI Specifications

• Supply voltage Core: 1.2V

I/O: 1.8V/2.85V/3.3V

• Maximum operating frequency: 40MHz

• Package: FBGA96

Principal Applications

• LCD display equipment

CDEX (Color Depth Expander)



Original



CDEX

Specifications

Absolute Maximum Ratings at Ta = 25°C, $DV_{SS} = 0V$, $AV_{SS}_OSC = 0V$

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage (I/O)	DV _{DD} IO		-0.3 to +3.96	V
Maximum supply voltage (core)	DV _{DD} CORE AV _{DD} OSC		-0.3 to +1.8	٧
Digital input voltage	VI		-0.3 to DV _{DD} _IO+0.3	V
Digital output voltage	Vo		-0.3 to DV _{DD} _IO+0.3	V
Operating temperature	Topr		-40 to +85	°C
Storage temperature	Tstg		-55 to +125	°C

Allowable Operating Ranges at $Ta=-40~to~+85^{\circ}C,~DV_{SS}=0V,~AV_{SS_OSC}=0V$

Danamatan	O. was boat	O and distance		Ratings			
Parameter	Symbol	Conditions	min	typ	max	unit	
Supply voltage (I/O)	DV _{DD} IO		2.6	2.85	3.6	V	
			1.7	1.8	1.9	V	
Supply voltage (I/O)	DV _{DD} CORE AV _{DD} OSC		1.0	1.2	1.3	V	
Input voltage range	V _{IN}		0		DV _{DD} _IO	V	

DC Characteristics at Ta = -40 to +85°C, $DV_{SS} = 0V$, $AV_{SS}_OSC = 0V$,

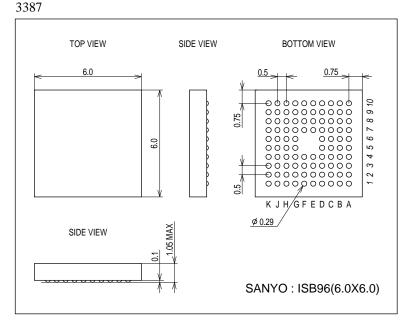
 $DV_{\mbox{\scriptsize DD_IO}} = 1.7V$ to 1.9V or 2.6V to 3.6V, $DV_{\mbox{\scriptsize DD_CORE}} = 1.0V$ to 1.3V

Parameter	Symbol	Conditions		Ratings			
Faianielei	Symbol	Conditions	min	typ	max	unit	
Input high-level voltage	VIH	CMOS level inputs	0.7DV _{DD} IO			V	
		CMOS level Schmitt inputs	0.7DV _{DD} _IO			V	
Input low-level voltage	VIL	CMOS level inputs			0.3DV _{DD} _IO	V	
		CMOS level Schmitt inputs			0.3DV _{DD} _IO	V	
Input high-level current	lн	V _I =DV _{DD} _IO			10	μΑ	
		V _I =DV _{DD} IO, with pull-down resistance			100	μА	
Input low-level current	I _{IL}	V _I =DV _{SS}	-10			<u>.</u> μΑ	
Output high-level voltage	VOH	CMOS voltage: 2.6V to 3.6V				μ, ,	
Catpat high lover veltage	1 *OH	Pin D: I _{OH} =-2mA					
		Pin F: I _{OH} =-2mA (when set to 2mA)					
		I _{OH} =-4mA (when set to 4mA)	DV _{DD} _IO-0.4			V	
		Pin G: I _{OH} =-4mA (when set to 4mA)	DD			-	
		I _{OH} =-8mA (when set to 8mA)					
		Pin H: I _{OH} =-4mA					
		CMOS voltage: 1.7V to 1.9V					
		Pin D: I _{OH} =-1mA					
		Pin F: I _{OH} =-1mA (when set to 2mA)					
		I _{OH} =-2mA (when set to 4mA)	DV _{DD} _IO-0.45			V	
		Pin G: I _{OH} =-2mA (when set to 4mA)	DVDD_10-0.43			V	
		I _{OH} =-4mA (when set to 4mA)					
		Pin H: I _{OH} =-2mA					
Output low-level voltage	V _{OL}	CMOS			0.4	V	
Output leak current	loz	At output of high-impedance	-10		10	μА	
Pull-down resistor	R _{DN}	Typical conditions:	-10		10	μΛ	
T dil-down resistor	NDN	Ta=25°C					
				98		kΩ	
		DV _{DD} _IO=2.85V					
Dynamic supply current	Innon	DV _{DD} _CORE=1.2V Typical conditions:					
Dynamic supply current	IDDOP	Ta=25°C					
				18		mΛ	
		DV _{DD} _IO=2.85V		10		mA	
		DV _{DD} _CORE=1.2V					
		tck=10MHz 10 steps	+				
		Typical conditions:					
		Ta=25°C					
		DV _{DD} _IO=2.85V		57		mA	
		DV _{DD} _CORE=1.2V					
<u> </u>		tck=40MHz 10 steps					
Static supply current *1	IDDST	Typical conditions:					
		Ta=25°C					
		DV _{DD} _IO=2.85V		20		μΑ	
		DV _{DD} _CORE=1.2V		20		μιτ	
		Outputs open					
		$V_{I}=DV_{SS}$ or DV_{DD} _IO	1				

^{*1:} There is a input terminal which builds in pull down resistance. Please note that there is no guarantee about static consumption current depending on circuit composition.

Package Dimensions FBGA96

unit:mm (typ)



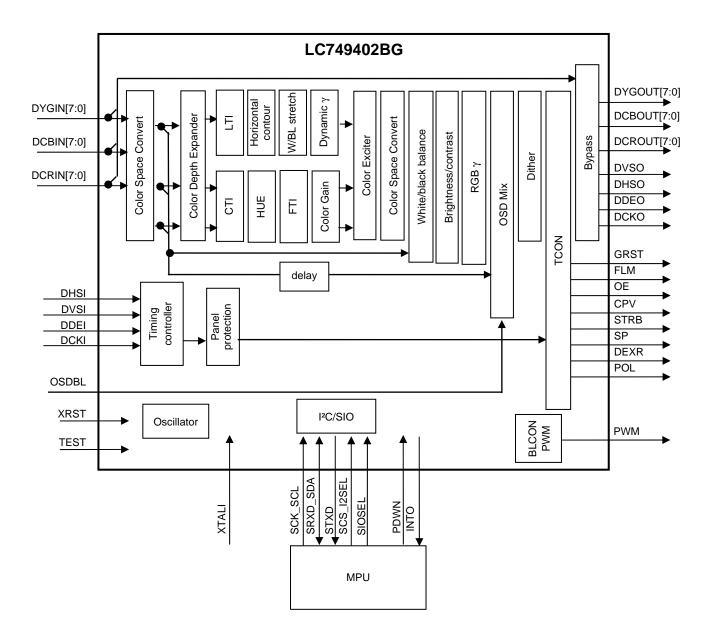
Pin Assignment

LC749402BG

2 3 4 5 6 7 10 0 0 0 0 0 0 0 0 Α 0 0 0 0 0 0 0 0 В 0 0 0 0 0 0 0 0 С 00000000 D 0000 Е 0 0 0 0 F 0 0 0 0 0 0 0 0 G 00000000 Н 00000000 J 0 0 0 0 0 0 0 0 Κ

Top view

Block Diagram



Pin Functions

Din No Din oumbel		In/output format		Connecting		Domostro
Pin No.	Pin symbol	I/O	Format	destir	nation	Remarks
A1	AV _{DD} OSC	Р	-	Core voltage	Analog	Connect this pin to B2 without fail.
A2	STXD	0	D	CMOS	Digital	SIO data
А3	SCK_SCL	I	С	CMOS	Digital	Bus clock (common to SIO and I ² C)
A4	DBOUT7	0	F	CMOS	Digital	B/Cb/C video (MSB)
A5	DBOUT4	0	F	CMOS	Digital	B/Cb/C video
A6	DBOUT1	0	F	CMOS	Digital	B/Cb/C video
A7	DGOUT6	0	F	CMOS	Digital	G/Y video
A8	DGOUT4	0	F	CMOS	Digital	G/Y video
A9	DGOUT3	0	F	CMOS	Digital	G/Y video
A10	DV _{DD} IO	Р	-	IO voltage	Digital	Connect this pin to B9 without fail
B1	RC_BIAS	I	J	resistor	Analog	Bias resistor connection (Connect this pin to GND with a $20k\Omega$)
B2	AV _{DD} OSC	Р	-	Core voltage	Analog	
В3	SRXD_SDA	I/O	Н	CMOS	Digital	SIO data input/I ² C data I/O
B4	PWM	0	D	CMOS	Digital	Pulse width modulation waveform
B5	DBOUT5	0	F	CMOS	Digital	B/Cb/C video
B6	DBOUT2	0	F	CMOS	Digital	B/Cb/C video (6-bit output mode, LSB)
B7	DGOUT7	0	F	CMOS	Digital	G/Y video (MSB)
B8	DGOUT5	0	F	CMOS	Digital	G/Y video
В9	DV _{DD} IO	Р	-	IO voltage	Digital	
B10	DGOUT2	0	F	CMOS	Digital	G/Y video (6-bit output mode, LSB)
C1	DCRIN0		С	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
C2	DCRIN1	I	С	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
C3	AV _{SS} _OSC	Р	-	GND	Analog	
C4	INTO	0	D	CMOS	Digital	Interrupt
C5	DBOUT6	0	F	CMOS	Digital	B/Cb/C video
C6	DBOUT3	0	F	CMOS	Digital	B/Cb/C video
C7	DBOUT0	0	F	CMOS	Digital	B/Cb/C video (8-bit output mode, LSB)
C8	DV _{DD} _IO	Р	-	IO voltage	Digital	
C9	DGOUT1	0	F	CMOS	Digital	G/Y video
C10	DGOUT0	0	F	CMOS	Digital	G/Y video (8-bit output mode, LSB)
D1	DCRIN2	I	С	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
D2	DCRIN3	I	С	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
D3	DCRIN4	I	С	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
D4	TEST	I	В	CMOS	Digital	Test (Normally, connect this pin to GND)
D5	XRST	I	А	CMOS	Digital	System reset ("L" reset)
D6	DV _{DD} _IO	Р	-	IO voltage	Digital	
D7	DV _{DD} IO	Р	-	IO voltage	Digital	
D8	DROUT7	0	F	CMOS	Digital	R/Cr video (MSB)
D9	DROUT6	0	F	CMOS	Digital	R/Cr video
D10	DROUT5	0	F	CMOS	Digital	R/Cr video

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Pin No.	Pin symbol	In/outp	ut format	Conne	ū	Remarks
1 111110.	1 III Symbol	I/O	Format	destin	ation	Remarks
E1	DCRIN5	I	С	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
E2	DCRIN6	I	С	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
E3	DCRIN7	ı	С	CMOS	Digital	R/Cr video (MSB).
				OWIGG	Digital	Connect this pin to GND when not to be used.
E4	DV _{SS}	Р	-	GND	Digital	
E7	PDWN	1	Α	CMOS	Digital	"H" power down.
	DDOLIT4			01100	Divisi	Connect this pin to GND when not to be used.
E8	DROUT4	0	F	CMOS	Digital	R/Cr video
E9	DROUT3	0	F	CMOS	Digital	R/Cr video
E10	DROUT2	0	F	CMOS	Digital	R/Cr video (6-bit output mode, LSB)
F1	DYGIN0	I	С	CMOS	Digital	G/Y/656 video (LSB). Connect this pin to GND when not to be used.
						G/Y/656 video.
F2	DYGIN1	I	С	CMOS	Digital	Connect this pin to GND when not to be used.
F2	DVCINO			CMOS	Digital	G/Y/656 video.
F3	DYGIN2	I	С	CMOS	Digital	Connect this pin to GND when not to be used.
F4	DV _{SS}	Р	-	GND	Digital	
F7	DV _{DD} _CORE	Р	-	Core voltage	Digital	
F8	DROUT1	0	F	CMOS	Digital	R/Cr video
F9	DROUT0	0	F	CMOS	Digital	R/Cr video (8-bit output mode, LSB)
F10	DCKO	0	G	CMOS	Digital	Video clock
G1	DYGIN3	ı	С	CMOS	Digital	G/Y/656 video.
<u> </u>	DIGINS	'	Ŭ	CIVIOS	Digital	Connect this pin to GND when not to be used.
G2	DYGIN4	ı	С	CMOS	Digital	G/Y/656 video.
						Connect this pin to GND when not to be used.
G3	DYGIN5	I	С	CMOS	Digital	G/Y/656 video. Connect this pin to GND when not to be used.
G4	DV _{SS}	Р	_	GND	Digital	Connect this pin to CND when not to be used.
G5	SCS_I2SEL	<u>.</u>	Α	CMOS	Digital	SIO chip enable/I ² C slave address switching
G6	SIOSEL	i I	С	CMOS	Digital	"L": I ² C slave, "H": 4-wire SIO
G7	DV _{DD} _CORE	<u>.</u> Р	-	Core voltage	Digital	2.1 6 slave, 11. 1 wile 6.6
G8	DHSO/SP2	0	F	CMOS	Digital	Horizontal synchronizing signal/start pulse signal for source
G9	DVSO/FLM2	0	F	CMOS	Digital	driver Vertical synchronizing signal/start pulse signal for gate
						driver
G10	DDEO	0	F	CMOS	Digital	Data enable signal
H1	DYGIN6	I	С	CMOS	Digital	G/Y/656 video. Connect this pin to GND when not to be used.
H2	DYGIN7	ı	С	CMOS	Digital	G/Y/656 video (MSB).
110	D\/			CND		Connect this pin to GND when not to be used.
H3	DV _{SS}	Р	-	GND		B/Cb/C video.
H4	DCBIN6	1	С	CMOS	Digital	Connect this pin to GND when not to be used.
H5	DVSI	ı	С	CMOS	Digital	Vertical synchronizing signal
						Data enable signal for external OSD.
H6	OSDBL	I	С	CMOS	Digital	Connect this pin to GND when not to be used.
H7	FLM	0	F	CMOS	Digital	Start pulse signal for gate driver
	DV _{DD} _CORE	Р	-	Core voltage	Digital	
H8						
H8 H9	DEXR	0	F	CMOS	Digital	Reversed video signal output for DTR. Low output when the DTR is OFF.

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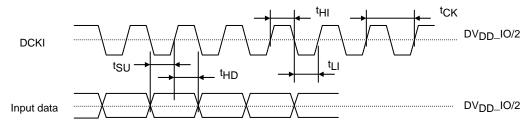
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Pin No.	Pin symbol		ut format	Conn	•	Remarks
		I/O	Format	destination		
J1	DCBIN0	ı	С	CMOS	Digital	B/Cb/C video (LSB). Connect to GND when not to be used.
J2	DVSS	Р	-	GND	Digital	
J3	DCBIN3	1	С	CMOS	Digital	B/Cb/C video. Connect this pin to GND when not to be used.
J4	DCBIN5	1	С	CMOS	Digital	B/Cb/C video. Connect this pin to GND when not to be used.
J5	DDEI	ı	С	CMOS	Digital	Data enable signal, Connect this pin to GND in the internal generation mode
J6	DHSI	1	С	CMOS	Digital	Horizontal synchronizing signal
J7	GRST	0	F	CMOS	Digital	Reset signal for gate driver
J8	CPV	0	F	CMOS	Digital	Clock signal for gate driver
J9	DV _{DD} CORE	Р	-	Core voltage	Digital	
J10	SP	0	F	CMOS	Digital	Start pulse signal for source driver
K1	DVSS	Р	-	GND	Analog	Connect this pin to J2 without fail
K2	DCBIN1	I	С	CMOS	Digital	B/Cb/C video. Connect this pin to GND when not to be used.
КЗ	DCBIN2	ı	С	CMOS	Digital	B/Cb/C video. Connect this pin to GND when not to be used.
K4	DCBIN4	ı	С	CMOS	Digital	B/Cb/C video. Connect this pin to GND when not to be used.
K5	DCBIN7	1	С	CMOS	Digital	B/Cb/C video (MSB). Connect this pin to GND when not to be used.
K6	DCKI	I	С	CMOS	Digital	Video clock
K7	XTAL1	I	С	CMOS	Digital	Panel protection, PWM generation clock. Connect this pin to GND when not to be used.
K8	OE	0	F	CMOS	Digital	Output enable signal for gate driver
K9	STRB	0	F	CMOS	Digital	Data strobe signal for source driver
K10	DV _{DD} CORE	Р	-	Core voltage	Digital	Connect this pin to J9 without fail

Pin Type

In/Output form	Function	Equivalent circuit	Application Terminal
III/Output IoIIII		Equivalent circuit	
А	Schmitt trigger CMOS input		XRST, PDWN, SCS_I2SEL
В	CMOS input with built-in pull-down resistor		TEST
С	CMOS input		SCK_SCL, SIOSEL, DVSI, DHSI, DDEI, OSDBL, DYGIN7, DYGIN6, DYGIN5, DYGIN4, DYGIN3, DYGIN2, DYGIN1, DYGIN0, DCBIN7, DCBIN6, DCBIN5, DCBIN4, DCBIN3, DCBIN2, DCBIN1, DCBIN0, DCRIN7, DCRIN6, DCRIN5, DCRIN4, DCRIN7, DCRIN6, DCRIN5, DCRIN4, DCRIN3, DCRIN2, DCRIN1, DCRIN0
D	2mA 3-STATE drive CMOS output		STXD, PWM, INTO
F	2mA/4mA switching 3-STATE drive CMOS output		DBOUT7, DBOUT6, DBOUT5, DBOUT4, DBOUT3, DBOUT2, DBOUT1, DBOUT0, DROUT7, DROUT6, DROUT5, DROUT4, DROUT3, DROUT2, DROUT1, DROUT0 DGOUT7, DGOUT6, DGOUT5, DGOUT4, DGOUT3, DGOUT2, DGOUT1, DGOUT0, DHSO/SP2, DVSO/FLM2, DDEO FLM, DEXR, POL, GRST, CPV, SP, OE, STRB
G	4mA/8mA switching 3-STATE drive CMOS output		DCKO
н	4mA 3-STATE drive CMOS input/output		SRXD_SDA
J	Analog input/output	—	RC_BIAS

I/O Timing

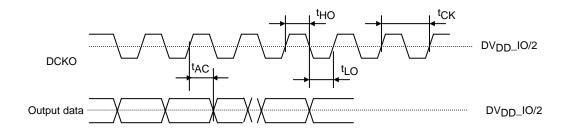
(1) Input data timing



Pin name	Parameter	Symbol	min	typ	max	unit
DCKI	Clock cycle	^t CK	25			ns
DONI	Duty			50		%
	Input data setup time (DV _{DD} _IO=2.6 to 3.6V)	t _{SU}	3			ns
DCRIN*, DYGIN*,	Input data setup time (DV _{DD} _IO=1.7 to 1.9V)	tsu	3			ns
DCBIN*, DVSI, DHSI, DDEI, OSDBL	Input data hold time (DV _{DD} _IO=2.6 to 3.6V)	^t HD	2			ns
	Input data hold time (DV _{DD} _IO=1.7 to 1.9V)	tHD	2			ns

^{*:} The recommended duty cycle of input clock is 50%

(2) Output data timing



Pin name	Parameter	Symbol	min	typ	max	unit
DOKO	Clock cycle	t _{CK}	25			ns
DCKO	Duty			50		%
	Output data delay time (DV _{DD} _IO=2.6 to 3.6V) Pin F: when set to 4mA Pin G: when set to 8mA	^t AC	-3		3	ns
DROUT*, DGOUT*, DBOUT*,	Output data delay time (DV _{DD} _IO=2.6 to 3.6V) Pin F: when set to 2mA Pin G: when set to 4mA	^t AC	-3		6	ns
DVSO, DHSO, DDEO, DEXR, POL, SP, STRB, CPV, OE, FLM, GRST	Output data delay time (DV _{DD} _IO=1.7 to 1.9V) Pin F: when set to 4mA Pin G: when set to 8mA	^t AC	-5		4	ns
	Output data delay time (DV _{DD} _IO=1.7 to 1.9V) Pin F: when set to 2mA Pin G: when set to 4mA	^t AC	-6		9	ns

^{*} When DCKO is set to the forward rotation output. Output load capacity: 5pF

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